

ULTRA-FAST RECOVERY RECTIFIER DIODES

MAIN PRODUCTS CHARACTERISTICS

$I_{F(AV)}$	2 x 8 A
V_{RRM}	200 V
$T_j (max)$	150°C
$V_F (max)$	0.99 V
$t_{rr} (max)$	30 ns

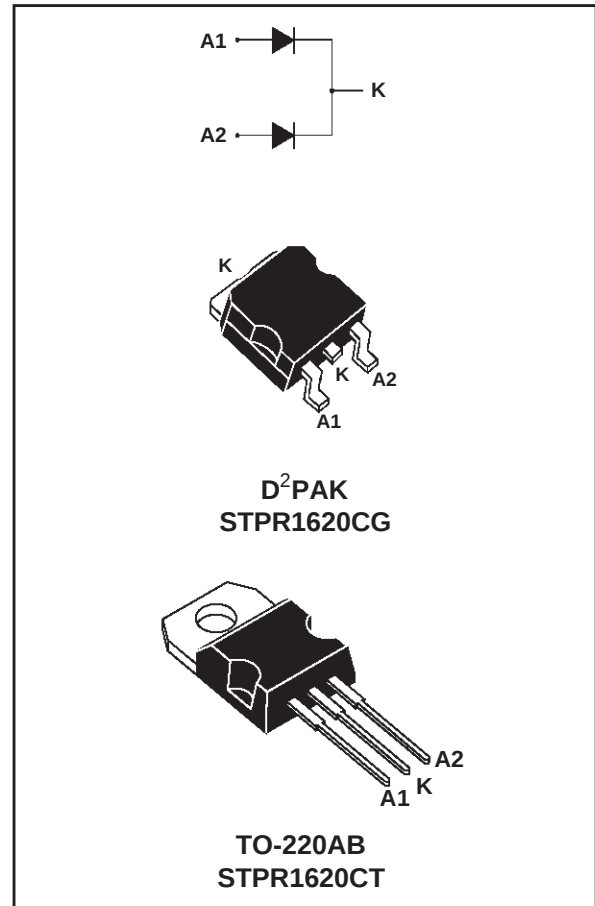
FEATURES

- SUITED FOR SMPS
- LOW LOSSES
- LOW FORWARD AND REVERSE RECOVERY TIME
- HIGH SURGE CURRENT CAPABILITY

DESCRIPTION

Low cost dual center tap rectifier suited for Switched Mode Power Supplies and high frequency DC to DC converters.

Packaged in D²PAK or TO-220AB, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.



ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter			Value	Unit
V _{RRM}	Repetitive peak reverse voltage			200	V
I _{F(RMS)}	RMS forward current			20	A
I _{F(AV)}	Average forward current δ = 0.5	T _c =120°C	Per diode Per device	8 16	A
I _{FSM}	Surge non repetitive forward current	t _p =10ms sinusoidal		80	A
T _{stg}	Storage temperature range			- 65 to + 150	°C
T _j	Maximum operating junction temperature			150	°C

STPR1620CG / STPS1620CT

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
R _{th(j-c)}	Junction to case	Per diode	3.0	°C/W
		Total	1.8	°C/W
R _{th(c)}		Coupling	0.6	°C/W

When the diodes 1 and 2 are used simultaneously :

$$\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)} (\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Test conditions		Min.	Typ.	Max.	Unit
I _R *	T _j = 25°C	V _R = V _{RRM}			50	μA
	T _j = 100°C			0.2	0.6	mA
V _F **	T _j = 125°C	I _F = 8 A		0.8	0.99	V
	T _j = 125°C	I _F = 16 A		0.95	1.20	
	T _j = 25°C	I _F = 16 A			1.25	

Pulse test : * tp = 5 ms, δ < 2 %

** tp = 380 μs, δ < 2 %

To evaluate the conduction losses use the following equation :

$$P = 0.78 \times I_{F(AV)} + 0.026 \times I_{F(RMS)}^2$$

RECOVERY CHARACTERISTICS

Symbol	Test conditions		Min.	Typ.	Max.	Unit
trr	T _j = 25°C	I _F = 0.5A I _R = 1A I _{rr} = 0.25A			30	ns
tfr	T _j = 25°C	I _F = 3A V _{FR} = 1.1 x V _F max dI _F /dt = 50 A/μs		20		ns
V _{FP}	T _j = 25°C	I _F = 3A dI _F /dt = 50 A/μs		3		V

Fig. 1: Average forward power dissipation versus average forward current (per diode).

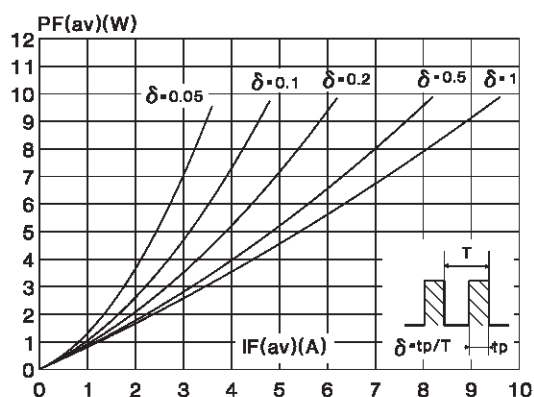


Fig. 2: Peak current versus form factor (per diode).

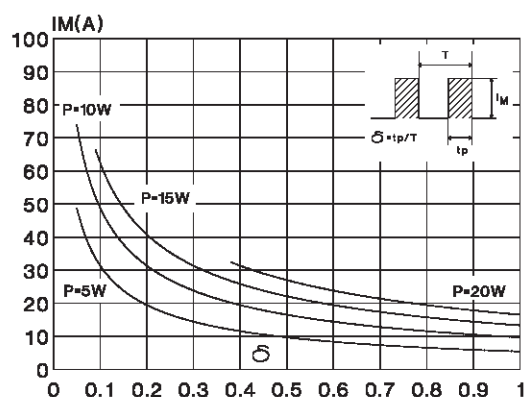


Fig. 3: Average current versus ambient temperature ($\delta : 0.5$, per diode).

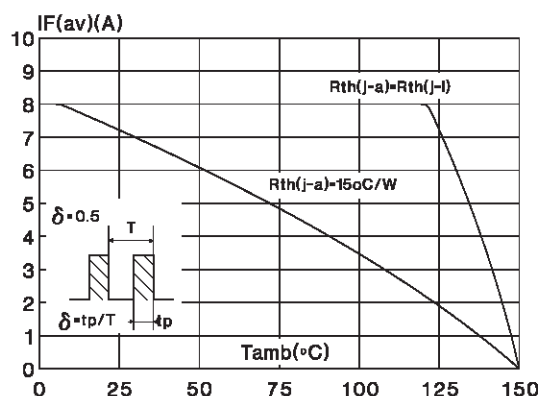


Fig. 4: Non repetitive surge peak forward current versus overload duration (maximum values, per diode).

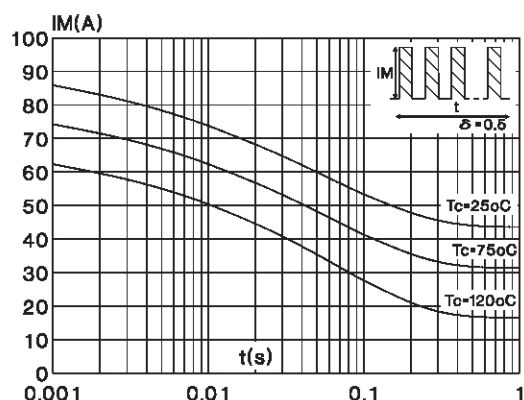


Fig. 5: Relative variation of thermal transient impedance junction to case versus pulse duration (per diode).

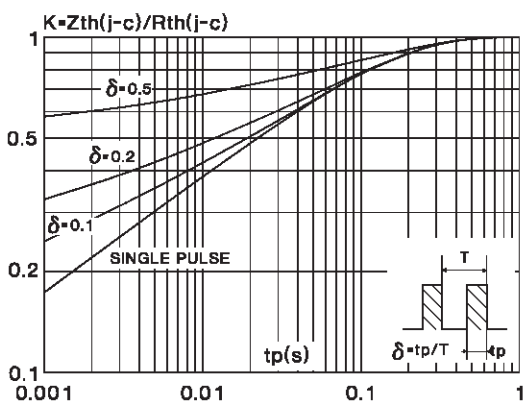


Fig. 6: Forward voltage drop versus forward current (maximum values, per diode).

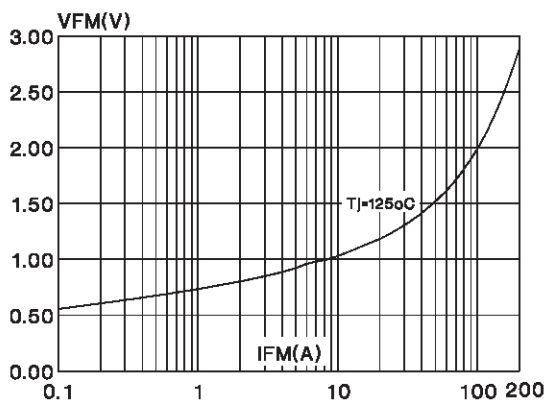


Fig. 7: Junction capacitance versus reverse voltage applied (typical values, per diode).

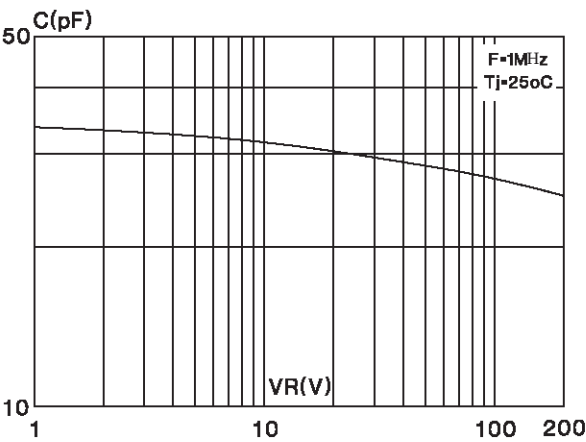


Fig. 8: Recovery charges versus dI_F/dt (per diode).

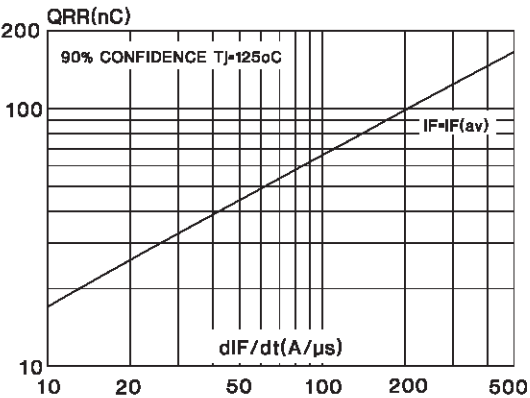


Fig. 9: Peak reverse current versus dI_F/dt (per diode).

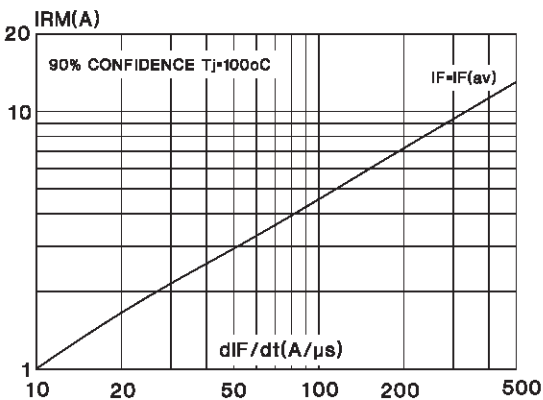
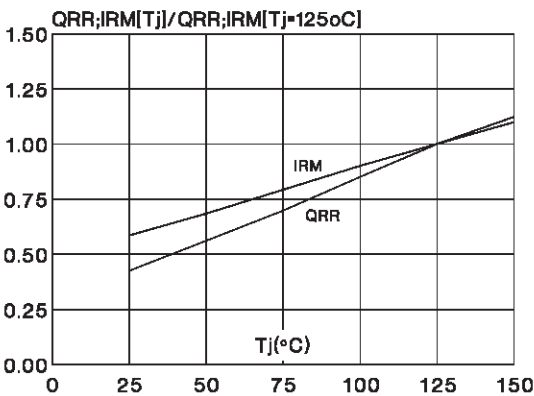
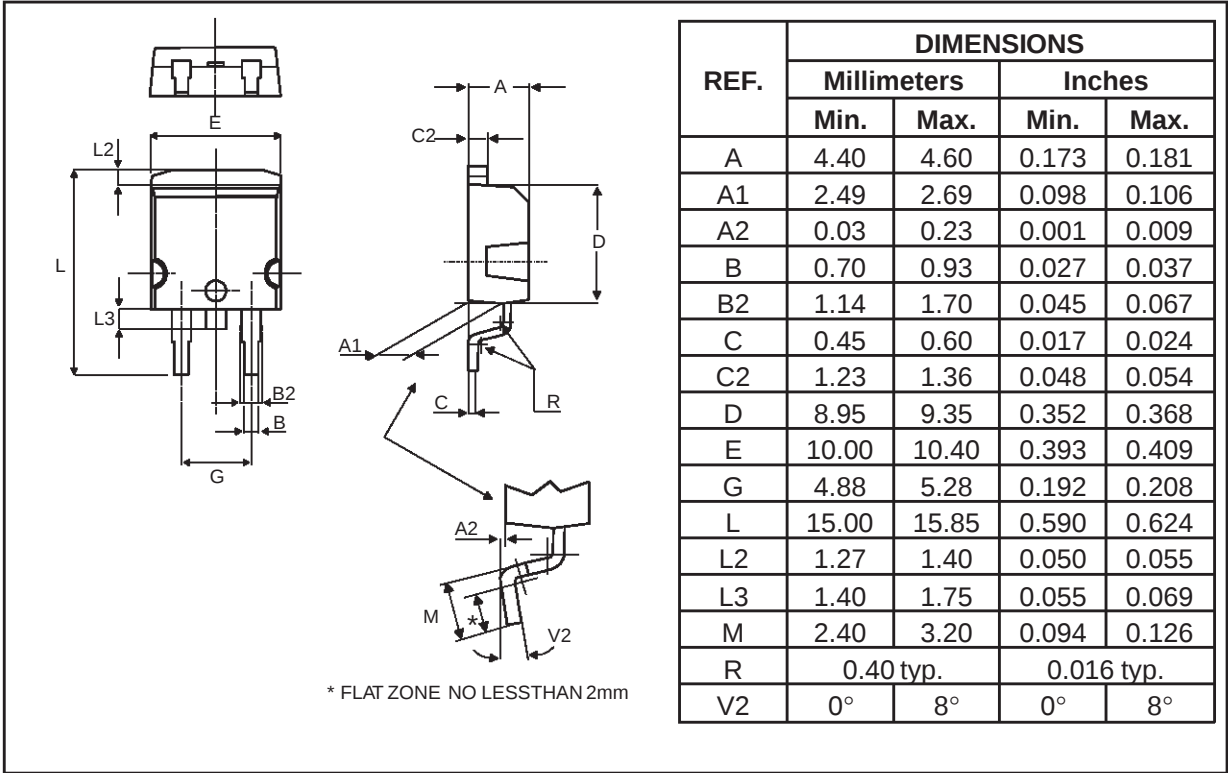


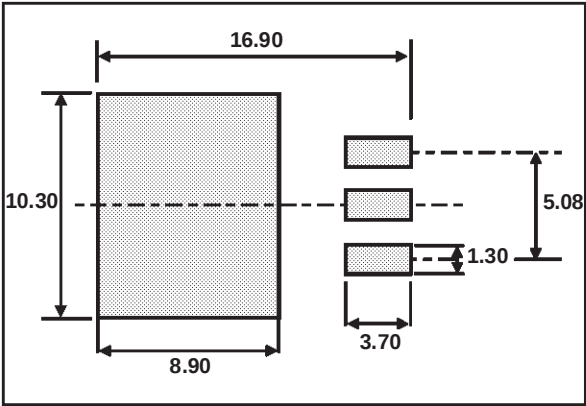
Fig. 10: Dynamic parameters versus junction temperature (per diode).



PACKAGE MECHANICAL DATA
D²PAK (Plastic)



FOOT PRINT (in millimeters)



STPR1620CG / STPS1620CT

PACKAGE MECHANICAL DATA

TO-220AB (JEDEC outline)

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
F2	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
G1	2.40	2.70	0.094	0.106
H2	10	10.40	0.393	0.409
L2	16.4 typ.		0.645 typ.	
L4	13	14	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam.	3.75	3.85	0.147	0.151

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPR1620CT	STPR1620CT	TO-220AB	2.23g	50	Tube
STPR1620CG	STPR1620CG	D ² PAK	1.48g	50	Tube
STPR1620CG-TR	STPR1620CG	D ² PAK	1.48g	1000	Tape & reel

- Cooling method : by conduction (C)
- Recommended torque value : 0.55N.m.
- Maximum torque value : 0.7N.m.
- Epoxy meets UL94,V0

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